

Please insert the following new claims:

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--20. A semiconductor device, comprising:

a substrate having a main surface and a back surface,

wherein said back surface has a central area, an intermediate area surrounding said central area and a peripheral area surrounding said intermediate area;

a semiconductor chip formed on said main surface;

a first bump unit formed in said central area of said back surface,

wherein said first bump unit radiates heat from said semiconductor device;

a second bump unit formed in said peripheral area of said back surface,

wherein said second bump unit transmits signals.

21. The semiconductor device in accordance with Claim 20, wherein said first bump unit includes a plurality of bumps that are formed a first distance apart from each other, and wherein said second bump unit includes a plurality of bumps that are formed a second distance apart from each other.